



28PH

2827

Practitioner's Docket No.: M-11443

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of (1st Inventor): Lee John Smith

Assignee: Amkor Technology, Inc.

Serial No.: 09/944,732-2003

Group No.: 2827

Filed: 08/31/2001

Examiner: David E. Graybill

For: "Thin Semiconductor Package Including Stacked Dies"

Date: March 24, 2003

Assistant Commissioner of Patents and Trademarks
Washington, D.C. 20231

STATUS INQUIRY

Sir:

More than twelve months have passed since the filing of this application on 08/31/2001. No communication has been received from the Patent and Trademark Office indicating action on this application.

Kindly advise the undersigned of the present status of this application.

Respectfully submitted,

James E. Parsons

Reg. No.34,691

Attorney for Applicant(s)

Customer No.:22888

Telephone: (408) 451-5906